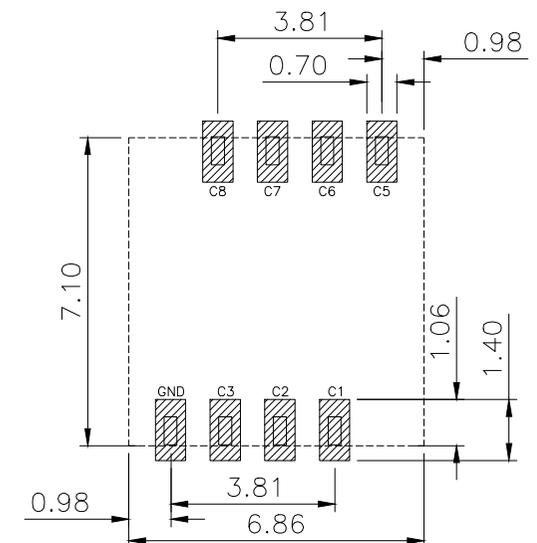
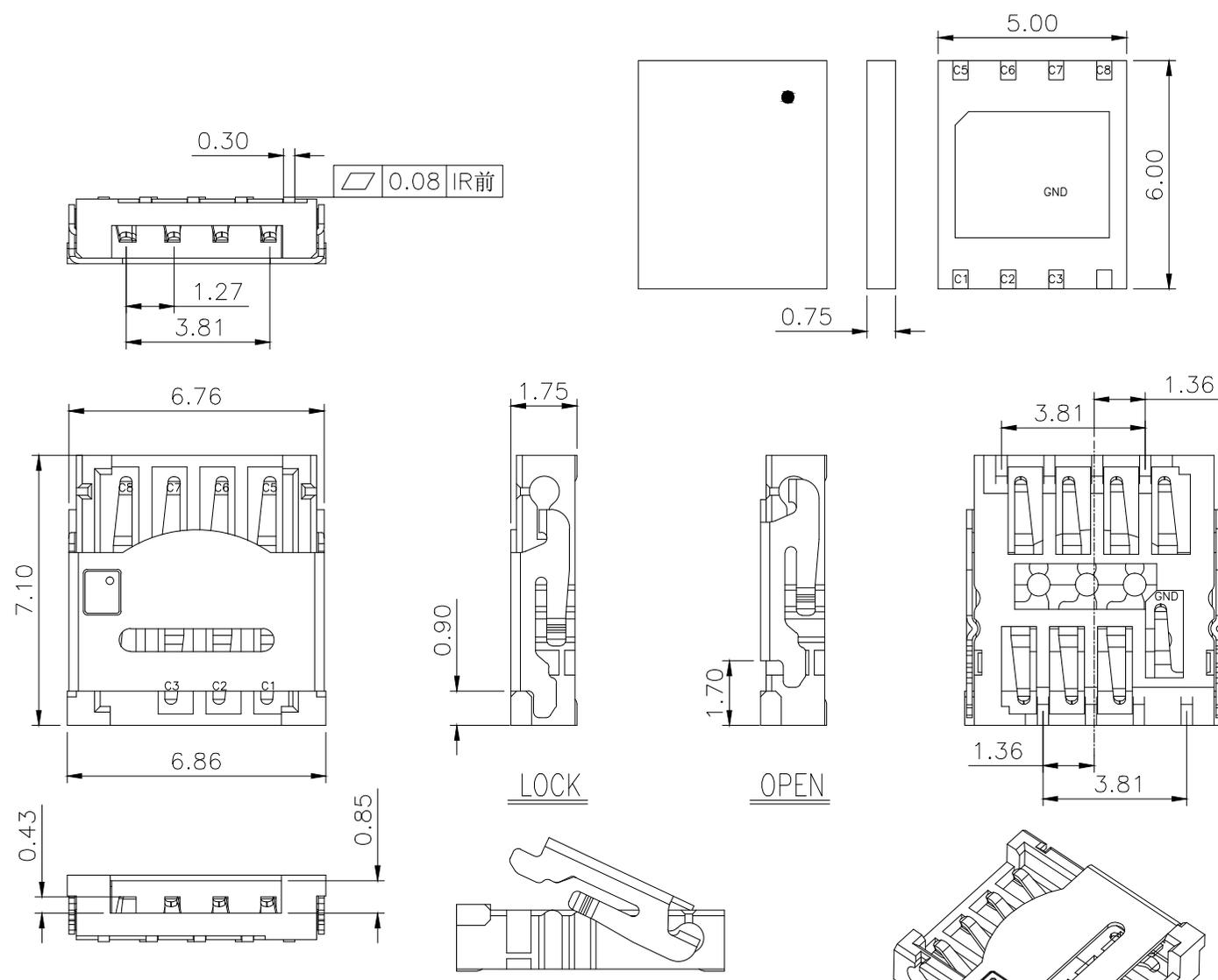


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2021/05/28



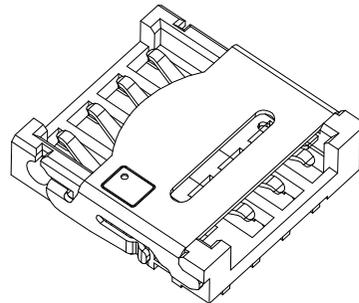
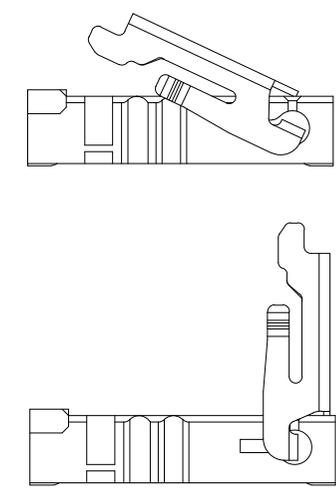
■ CIRCUIT TRACE KEEP OUT AREA

 ▨ SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.
RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

- 1) MATERIAL:
 - 1.1 HOUSING:LCP,UL94-V0,COLOR:BLACK
 - 1.2 OCONTACT:C5210-H
 - 1.3 SHELL:SUS304-H
- 2) FINISH:
 - 2.1 TERMINAL:50 u" Min.NICKEL PLATED OVERALL
 - 2.2 CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS;
- 3) ELECTRICAL CHARACTERISTICS

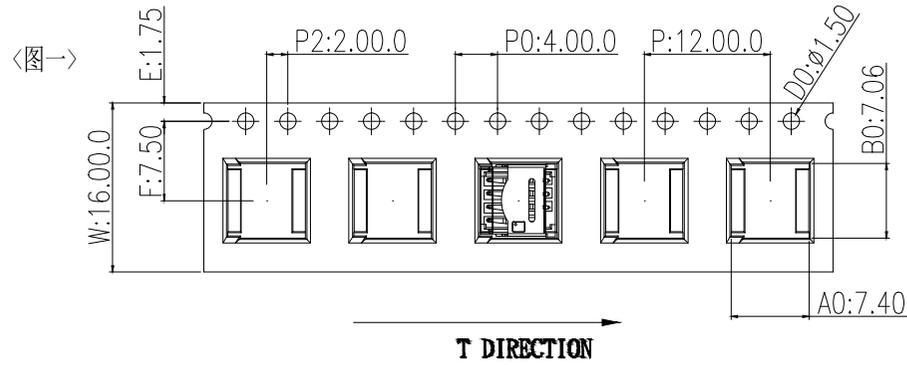
RATING CURRENT : 0.5A MAX.
 CONTACT RESISTANCE :50 mΩ MAX
 DIELECTRIC WITHSTANDING : 500V AC MIN.
 INSULATION RESISTANCE: 1000 MΩ MIN.

序号	触点信号	解释
1	VSS	接地
2	NULL	未定义
3	I/O	数据输入/数据端口
4	NULL	未定义
5	NULL	未定义
6	CLK	时钟信号输入端
7	RST	复位信号输入端
8	VDD	供电电压输入端



GENERAL TOLERANCE		DWG NO.	APPD:	Scale	1:1
X.±0.45	x.*±5°	Title	CHKD:	UNIT	mm
.X±0.35	.x*±2°	Part NO.	DR:		
.XX±0.25	.xx*±1°	JYS-ESIMI75-199	Date	2021/05/28	
.XXX±0.15	.xxx*±0.5°	Shenzhen JYSCONN Electronics Co., LTD.			
SHEET	1/2				

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2021.03.05

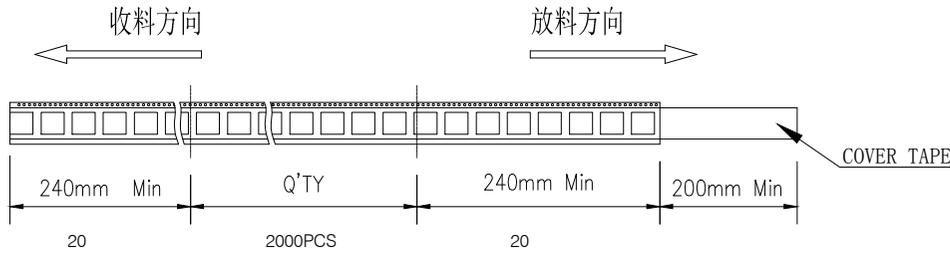


<图一>

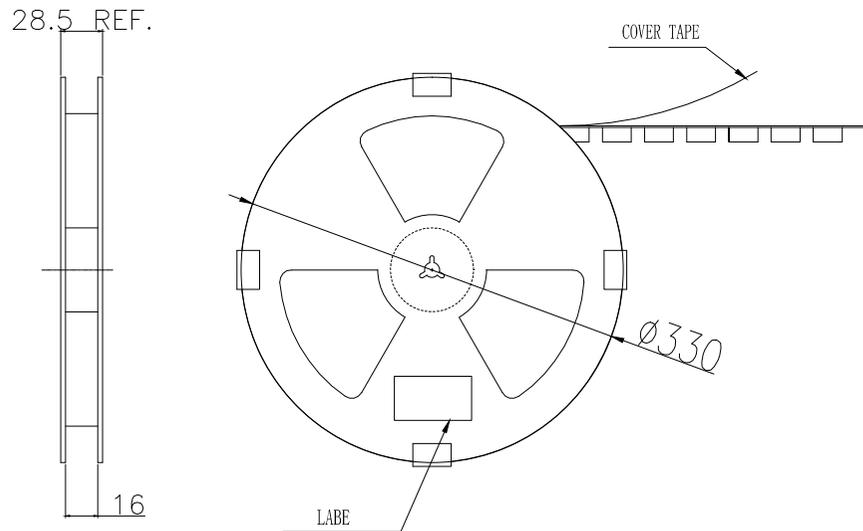
<图三>

<TABLE 1> PACKAGING QUANTITY

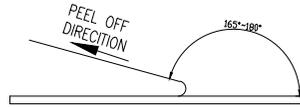
QTY/REEL	REEL/CARTON	QTY/CARTON
2000	15	30000



<图二>

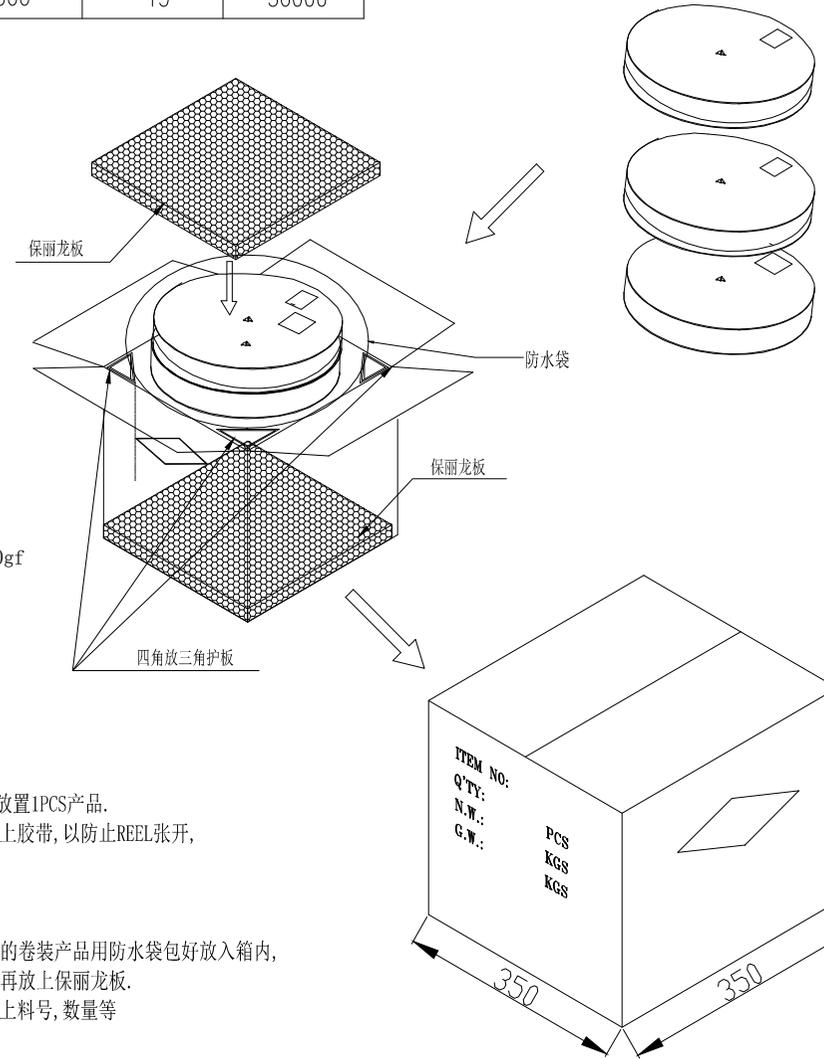


COVER TAPE PEELING FORCE:20gf~100gf



NOTE:

1. 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
2. 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
3. 包装数量见如<TABLE 1>示
4. 包装成箱见如<图三>示
箱底放保丽龙板, 再依次将指定数量的卷装产品用防水袋包好放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
5. 封箱, 在封好的纸箱上按客户要求写上料号, 数量等



GENERAL TOLERANCE		图号	设计		Peng	比例	1:1
X.±0.45	x.*±5°	品名	1.75H E SIM CARD 8PIN 抓盖式		审核	单位	mm
.X±0.35	.x±2°		包装图		核准		
.XX±0.25	.xx'±1°	料号	JYS-ESIM175-199	日期	2021/03/05		
.XXX±0.15	.xxx'±0.5°			JYSCONN Electronics Co., LTD.			
页号	2/2						